

IN THE CLAIMS

1. (Currently Amended) A method of producing an electrical circuit element comprising an elongate electrical conductor encircled by magnetic material extending along at least a part of said electrical conductor, the method comprising:
 - forming at least a first sacrificial layer above and across said part of said electrical conductor;
 - removing at least part of said first sacrificial layer to leave a space above and across said electrical conductor;
 - introducing a fluid comprising magnetic nanoparticles dispersed in a liquid dispersant into said space, and
 - removing said liquid dispersant leaving said magnetic nanoparticles densely packed in said space as at least part of said magnetic material.
2. (Previously presented) A method of producing an electrical circuit element as claimed in claim 1, including forming a support layer with a cavity, forming a layer of said magnetic material in said cavity, forming said electrical conductor over said layer of said magnetic material, and forming said first sacrificial layer overlapping said electrical conductor and said layer of said magnetic material.
3. (Currently Amended) A method of producing an electrical circuit element comprising an elongate electrical conductor encircled by magnetic material extending along at least a part of said conductor, the method comprising:
 - forming first and second sacrificial layers across said part of said electrical conductor respectively above and below the conductor;
 - removing at least parts of said sacrificial layers to leave a space encircling said electrical conductor;
 - introducing a fluid comprising magnetic nanoparticles dispersed in a liquid dispersant into said space, and
 - removing said liquid dispersant leaving said magnetic nanoparticles densely packed in said space as at least part of said magnetic material.

4. (Previously presented) A method of producing an electrical circuit element as claimed in claim 3, including forming a support layer with a cavity, forming said second sacrificial layer in said cavity, forming said electrical conductor over said second sacrificial layer, and forming said first sacrificial layer overlapping said electrical conductor and said second sacrificial layer.
5. (Currently Amended) A method of producing an electrical circuit element as claimed in claim 3 4, wherein said support layer comprises at least a first layer of electrically insulating material, and said electrical conductor is deposited over said second sacrificial layer and at least part of said first layer of electrically insulating material.
6. (Currently Amended) A method of producing an electrical circuit element as claimed in claim 5, wherein said first sacrificial layer is surrounded by a further layer of insulating material formed over ~~the first~~ said first layer of insulating material.
7. (Currently Amended) A method of producing an electrical circuit element as claimed in claim 1, wherein said at least a first sacrificial layer ~~or layers comprise~~ comprises an organic material.
8. (Currently Amended) A method of producing an electrical circuit element as claimed in claim 1, wherein said at least a first sacrificial layer ~~or layers comprise~~ comprises a photo-resist material, and producing said first sacrificial layer ~~or layers~~ includes forming a layer or layers of said photo-resist material, exposing said photo-resist material in a pattern defining the geometry of said first sacrificial ~~layers~~ layer and selectively removing photo-resist material, and removing said ~~parts~~ part of said first sacrificial ~~layers~~ layer comprises dissolving ~~them~~ said part in a solvent.
9. (Currently Amended) A method of producing an electrical circuit element as claimed in claim 1, wherein a further layer of sacrificial material is formed above said electrical conductor with at least one aperture corresponding to said space to contain said fluid before removal of said liquid dispersant.

10. (Previously presented) A method of producing an electrical circuit element as claimed in claim 1, and comprising forming a protective layer over said magnetic material (2).
11. (Previously presented) A method of producing an electrical circuit element as claimed in claim 1, wherein said magnetic nanoparticles are ferromagnetic.
12. (Currently Amended) A method of producing an electrical circuit element as claimed in claim 1, wherein said magnetic material presents an easy axis of magnetisation extending along said electrical conductor.
13. (Currently Amended) A method of producing an electrical circuit element as claimed in claim 1, wherein removing said liquid dispersant comprises evaporating it.
14. (Currently Amended) A method of producing an electrical circuit element as claimed in claim 1, and comprising applying a magnetic field to said magnetic material while said liquid dispersant is being removed.
15. (Previously presented) An electrical circuit element produced by a method as claimed in claim 1.
16. (Currently Amended) A meander-type inductive element comprising:
 - a plurality of juxtaposed substantially parallel electrical circuit elements as claimed in claim 15 and at least one electrical interconnection between adjacent ends of the electrical conductors of respective ones of said juxtaposed substantially parallel electrical circuit elements.
17. (New) A method of producing an electrical circuit element as claimed in claim 1, the method comprising:
 - forming a second sacrificial layer across said part of said electrical conductor below the conductor;
 - removing at least parts of said first and second sacrificial layers to leave a space encircling said electrical conductor;

introducing said fluid comprising magnetic nanoparticles dispersed in a liquid dispersant into said space above and below the conductor, and

removing said liquid dispersant leaving said magnetic nanoparticles densely packed in said space above and below the conductor as at least part of said magnetic material.